Event Advisory: Distinguished Panel to Explore New Dimensions in Scaling at Applied Materials Symposium

May 23, 2008

SANTA CLARA, Calif.--(BUSINESS WIRE)--May 23, 2008--Progress in advanced semiconductor technology depends on the industry's ability to continuously change and reinvent itself. On June 2nd Applied Materials, Inc. will host an evening of presentations and discussion exploring the strategies needed to scale device performance, functionality and cost for the next decade. A panel of industry executives will share their perspectives on advancements in lithography and patterning materials, new design layouts, 3D integration and novel packaging schemes that are expected to drive greater device densities and process efficiencies.

Titled "New Dimensions to Moore's Law," this important event will take place in conjunction with the prestigious International Interconnect Technology Conference (IITC) in Burlingame, CA.

Panel:
Dan Hutcheson, VLSI Research
Chris Malachowsky, nVidia Corporation
Klaus Schuegraf, SanDisk Corporation
Scott Becker, Tela Innovations
Tom St. Dennis, Applied Materials

Where:
The Hyatt Regency at San Francisco Airport,
1333 Bayshore Highway, Burlingame, CA 94010

When:
Monday, June 2nd, 2008

Schedule:
5:00pm Registration and Reception
6:15pm Panel and Q&A

For event registration, please visit www.appliedmaterials.com/2008_IITC

Applied Materials, Inc. (Nasdaq:AMAT) is the global leader in Nanomanufacturing Technology(TM) solutions with a broad portfolio of innovative equipment, service and software products for the fabrication of semiconductor chips, flat panel displays, solar photovoltaic cells, flexible electronics and energy efficient glass. At Applied Materials, we apply Nanomanufacturing Technology to improve the way people live. Learn more at www.appliedmaterials.com.

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